Optoelectronic Neural Networks for Switching Heriot-Watt University M. R. Taghizadeh, J. F. Snowdon, A. J. Waddie (R. A.) and K. J. Symington (Ph. D. student). Project funded by EPSRC "Optoelectronic Switch Controller for Telecommunications" grant.

- resource allocation.













Modified Hopfield Neural Network



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Diffractive Optic Element (DOE) for Hopfield Neural Network

The neural network requires a highly uniform pattern only attainable by using a lowefficiency binary element. Additionally the large period of the detector array forces the DOE to have a small (~80µm) period limiting the number of pixels available to optimise the grating.





Graph of Intensity versus Order

Order

Phase-only DOEs are created by selectively etching fused silica to form phase profiles which have been optimised to produce the desired intensity patterns in the far-field of a Fourier lens. Elements with efficiencies of >70% and non-uniformities of <3% are routinely produced by the Diffractive Optics Group at Heriot-Watt University. These elements are used as array generators and interconnection elements as well as more

complex beam shaping elements for laser material processing.



Sample DOE

Why Use Free-Space Optics?

0.02

0.018

0.016

0.014

0.012

0.01

0.008

0.006

0.004

0.002

Neural networks use simple processing elements where communication is an integral part of their design. Electronics has difficulty implementing scalable non-local interconnects whereas light is non-interacting in free space and therefore the interconnects can effectively cross each other.



Future Directions

Using 'Flip-Chip' bonding it would be possible to integrate both VCSEL and Detector arrays. This would ultimately allow the creation of a Folded System.



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Binary Amplitude Mask

Smart-Pixels

Solder-bumps facilitate the combination of conventional Si-based electronics with optoelectronic components using a process called flip-chip bonding. This hybrid technology allows processing planes of arbitrary functional complexity to be created.



Solder bumps ready for flipchip bonding process.

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Another alternative is to attempt implementation of an Optoelectronic Bidirectional Associative Memory (OBAM).



OBAM Layout Mirror 2



The BAM has weighted interconnects between the input and output layers but not within the layers. The weighted interconnects are defined by the input and associated output patterns the network is to learn.

The bipolar neurons limit the total number of weight values required to implement the BAM to 2P+1 where P is the number of input/output sets the network is to learn.

10 Input - 10 Output OBAM

